DC-033-AXXX
W9.30xD8.00xH5.30

技术参数 / Technical parameter

插座内芯(Inner core) ： Φ 1.0/Φ 1.3	耐电压(Withstand voltage) ： 500V AC for 1 min
插座外孔(Outer hole)：Φ 4.2	操作寿命(Operation life)：5,000 Cycles Min
温度范围(Operating temp)：-20°C TO +70°C	插拔力(Operating force)：3~20N
额定负荷(Rated load)：DC 30V 1A	焊接方式(Welding mode)：贴片式/SMT
接触电阻(Contact resistance)：≤0.03Ω	包装方式(Packaging method)：散装/Bulk
绝缘电阻(Insulation resistance)：≥100MΩ	最小包装(Minimum packing)：1,000/PCS

外形尺寸(UNIT:MM) / Size Chart

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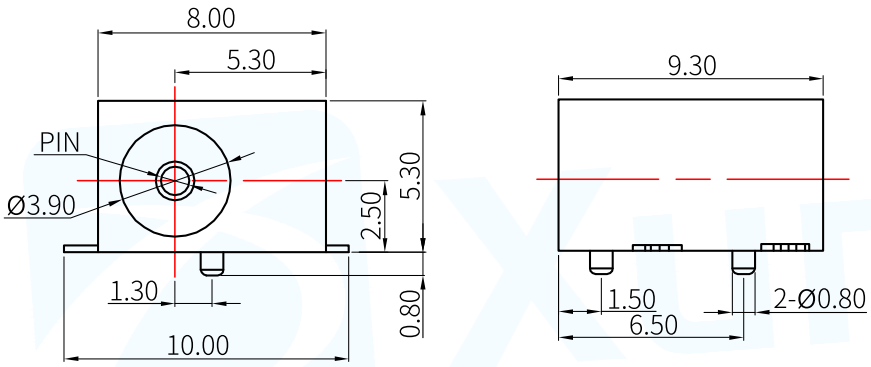
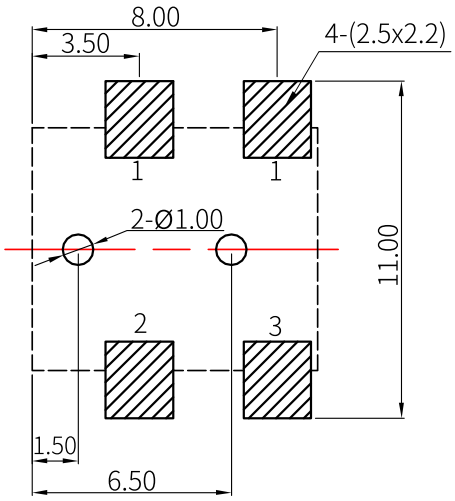
更多资料请参考技术选型档！

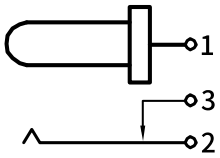


Pin	Part No	Current
¢ 1.0	DC-033-A100	1.0A
¢ 1.3	DC-033-A130	1.0A
¢ 1.65	DC-033-A165	1.0A

线路板安装(UNIT:MM) / Mounting Dimensions



P.C.B LAYOUT(copper-side view)



CIRCUIT DIAGRAM

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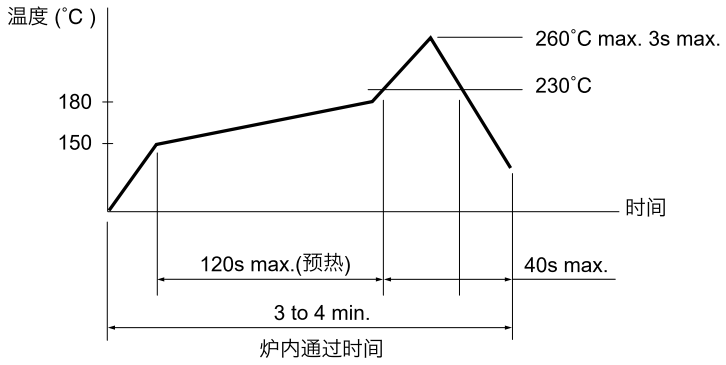
焊接条件 / Welding conditions

回流焊/Reflow soldering

适用表面贴装型产品/Applicable to surface mount products

温度分布/Temperature distribution



注:

1. 加热方式:以远红外线上下加热方式。
2. 温度测量:用Φ0.1~0.2 的 CA(K)或 CC(T)测量位置在焊接连接部(锡/铜箔面)。
3. 固定方式:采用耐热胶带。

手焊式/Hand welding

项目/Project	条件/condition
焊接温度 Welding temperature	350°C max.
持续焊接时间 Continuous welding time	3s max.
焊剂斗容量 Flux bucket capacity	60W max.

浸焊式/Immersion soldering

项目/Project	条件/condition
助焊剂附着量 Flux adhesion	不附着于零部件贴装面的程度 Not attached to the mounting surface of components
预热温度 Preheating temperature	印刷电路板焊接面的周围温度 100°C max. The temperature around the welding surface of PCB is 100 °C max
预热温度时间 Preheat temperature time	60s max.
焊接温度 welding temperature	260°C max.
焊接浸渍时间 Welding immersion time	5s max.
焊接次数 Welding times	2 times max.

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